

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1.-21. (Cancelled)

22. (Original) A method for selectively altering the adhesive strength of a polishing pad adhesive layer, comprising:

providing a mask having a transparent region and an opaque region;
directing radiation toward the mask so that the radiation is blocked by the opaque region and passes through the transparent region to impinge on the adhesive layer on the polishing pad, whereby the area of the adhesive layer corresponding to the transparent region of the mask is cured to be less adhesive.

23. (Original) The method of claim 22 wherein the radiation is ultraviolet light.

24. (Original) The method of claim 23 wherein the transparent region is made of ultraviolet light transparent quartz or polymer material.

25. (Original) The method of claim 23 wherein the mask is made of ultraviolet light blocking material.

26. (Original) The method of claim 25 wherein the mask is made of metal.

27. (Original) The method of claim 25 wherein the mask is made of ceramic or polymer material.

28. (Original) The method of claim 25 wherein the mask is made of paper.
29. (Original) The method of claim 22 wherein the transparent region is an opening.
30. (Original) The method of claim 22 wherein the transparent region and the opaque region form concentric circles.
31. (Original) The method of claim 22 wherein there are a plurality of transparent and opaque regions.
32. (Original) The method of claim 31 wherein the transparent regions are circles.
33. (Original) The method of claim 31 wherein the transparent regions are arc segments.
34. (Original) The method of claim 22 wherein a ratio of a surface area of the cured region to a surface area of the adhesive region is between about 10% to 30%.
35. (Original) The method of claim 22 wherein the polishing pad is exposed to the radiation for a time between about 5 to 60 seconds.
36. (Original) The method of claim 23 wherein the radiation intensity is between about 100 to 1200 Watts/inch.
37. (Original) A method for selectively altering the adhesive strength of a polishing pad adhesive layer, comprising:
 - providing a polishing pad having a layer of adhesive that covers substantially an entire surface of the pad; and
 - curing selected portions of the adhesive layer to reduce adhesive strength of the layer.

38. (New) The method of claim 37 wherein:
curing includes directing radiation toward the adhesive layer.
39. (New) The method of claim 38, further comprising:
positioning a mask between the adhesive layer and a source of radiation, where
the mask has a transparent and a non-transparent portion, the non-transparent portion blocks a
fraction of the radiation from the adhesive layer so that only a selected area of the adhesive layer
is cured.
40. (New) The method of claim 37, wherein:
the adhesive is partially cured.
41. (New) The method of claim 37, wherein:
the adhesive is fully cured.
42. (New) The method of claim 37, wherein:
the adhesive is acrylic based.
43. (New) The method of claim 25, wherein:
the mask is made of borosilicate glass.
44. (New) The method of claim 22, wherein:
the transparent region is in the center of the mask.
45. (New) The method of claim 22, wherein:
the adhesive is rubber based.